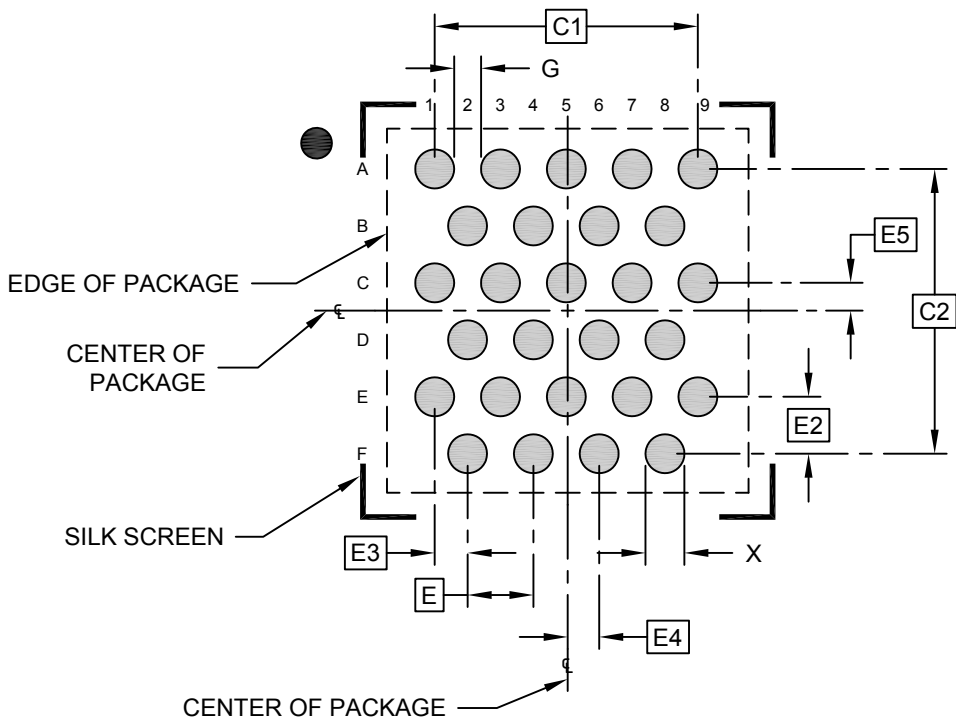


# 27-Ball Wafer Level Chip Scale Package (CS) - 2.199x2.215x0.483 mm Body [WLCSP]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



## RECOMMENDED LAND PATTERN

		MILLIMETERS		
	Units	MIN	NOM	MAX
Contact Pitch	E	0.40 BSC		
Contact Pitch	E2	0.35 BSC		
Contact Pitch	E3	0.20 BSC		
Contact Offset	E4	0.191 BSC		
Contact Offset	E5	0.169BSC		
Contact Diameter	X			0.24
Contact Pad Spacing	C1	1.60 BSC		
Contact Pad Spacing	C2	1.73 BSC		
Contact Pad to Contact Pad (Xnn)	G2	0.16		

**Notes:**

1. Dimensioning and tolerancing per ASME Y14.5M  
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
2. Ball pattern is not centered on the package.